LCD / LCM SPECIFICATION



WINSTAR Display Co.,Ltd. 華凌光電股份有限公司





Winstar Display Co., LTD 華凌光電股份有限公司



SPECIFICATION

CUSTOMER :	~ ()
MODULE NO.:	WG24064A-TMI-VZ#

APPROVED BY:		
FOR CUSTOMER USE ONLY)	PCB VERSION:	DATA:

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY
15			

VERSION	DATE	REVISED PAGE NO.	SUMMARY
K	2017/07/03		Modify IDD



Winstar Display Co.,

MODLE NO:

華凌光電股份有限公司

RECORDS OF REVISION

DOC. FIRST ISSUE

VERSION	DATE	REVISED PAGE NO.	SIIMMARY
0	2009/11/24		First issue
A	2010/04/26		Modify IC=RA6963
В	2012/10/16		Modify backlight
			information.
С	2013/05/20		Remove IC information
D	2014/12/10	(C	Modify length of cable.
Е	2015/11/11		Modify Response Time
F	2016/01/27		Modify Precautions in use
			of LCD Modules
			& Static electricity test
G	2016/06/22		Correct Contour Drawing
			Modify Module dimension
			13.0mm
H	2016/12/29		Modify IDD
I	2017/01/19		Modify VIL & B/L
			information
J	2017/01/24		Modify IDD
K	2017/07/03		Modify IDD



Contents

- 1.Module Classification Information
- 2.Precautions in use of LCD Modules
- 3.General Specification
- 4. Absolute Maximum Ratings
- 5. Electrical Characteristics
- 6. Optical Characteristics
- 7.Interface Pin Function
- 8. Contour Drawing & Block Diagram
- 9.Reliability
- 10.Backlight Information
- 11.Inspection specification
- 12. Material List of Components for RoHs
- 13.Recommendable Storage



1. Module Classification Information

① Brand: WINSTAR DISPLAY CORPORATION

② Display Type: H→Character Type, G→Graphic Type, X→TAB Type, O→COG Type

③ Display Font: 240 * 64 dot

Model serials no.

 $B \rightarrow EL$, Blue green $A \rightarrow LED$, Amber $L \rightarrow LED$, Full color $D \rightarrow EL$, Green $R \rightarrow LED$, Red $J \rightarrow DIP \ LED$, Blue $W \rightarrow EL$, White $O \rightarrow LED$, Orange $K \rightarrow DIP \ LED$, White

M→EL, Yellow Green G→LED, Green E→DIP LED, Yellow Green

F \rightarrow CCFL, White P \rightarrow LED, Blue H \rightarrow DIP LED, Amber Y \rightarrow LED, Yellow Green X \rightarrow LED, Dual color I \rightarrow DIP LED, Red

 $G\rightarrow$ LED, Green $C\rightarrow$ LED, Full color

© LCD Mode : B→TN Positive, Gray V→FSTN Negative, Blue

N→TN Negative, T→FSTN Negative, Black

L→VA Negative D→FSTN Negative (Double film)

 $H \rightarrow HTN$ Positive, Gray $F \rightarrow FSTN$ Positive $I \rightarrow HTN$ Negative, Black $K \rightarrow FSC$ Negative $U \rightarrow HTN$ Negative, Blue $S \rightarrow FSC$ Positive

M→STN Negative, Blue E→ISTN Negative, Black
G→STN Positive, Gray C→CSTN Negative, Black
Y→STN Positive, Yellow Green A→ASTN Negative, Black

② LCD Polarize A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00

Type/ Temperature D→Reflective, N.T, 12:00 K \rightarrow Transflective, W.T,12:00 range/ View G \rightarrow Reflective, W. T, 6:00 C \rightarrow Transmissive, N.T,6:00 direction J \rightarrow Reflective, W. T, 12:00 F \rightarrow Transmissive, N.T,12:00 B \rightarrow Transflective, N.T,6:00 I \rightarrow Transmissive, W. T, 6:00

E \rightarrow Transflective, N.T.12:00 I \rightarrow Transmissive, W.T, 0:00 L \rightarrow Transmissive, W.T,12:00

Special Code
V : Built in Negative Voltage

Z:ICNT7086

#:Fit in with the ROHS Directions and regulations



2. Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Winstar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Winstar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Winstar have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.





3.General Specification

Item	Dimension	Unit
Number of dots	240 x 64	_
Module dimension	180.0 x 65.0 x 13.0	mm
View area	133.0 x 39.0	mm
Active area	127.16 x 33.88	mm
Dot size	0.49 x 0.49	mm
Dot pitch	0.53 x 0.53	mm
LCD type	STN Negative, Blue Transmissive (In LCD production, It will occur slightly color of can only guarantee the same color in the same based on the same based o	
Duty	1/64	
View direction	6 o'clock	
Backlight Type	LED White	
IC	RA6963	



4.Absolute Maximum Ratings

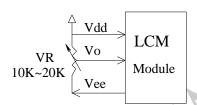
Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	Тор	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	Tst	-30	_	+80	$^{\circ}\!\mathbb{C}$
Input Voltage	V _{IN}	-0.3	_	V _{DD} +0.3	V
Supply Voltage For Logic	$ m V_{DD} ext{-}V_{SS}$	-0.3	_	+7.0	V



5.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	V_{DD} - V_{SS}	_	3.0	_	5.5	V
		Ta=-20°C	_	_	13.9	V
Supply Voltage For LCD	V_{DD} - V_{0}	Ta=25°C	12.1	12.5	12.9	V
*Note		Ta=70°C	10.1	_	<- X	V
Input High Volt.	$V_{ m IH}$	_	0.8V _{DD}	_	V_{DD}	V
Input Low Volt.	V_{IL}	_	0	^− C	$0.15~\mathrm{V_{DD}}$	V
Output High Volt.	V _{OH}	_	V _{DD} -0.3		$V_{ m DD}$	V
Output Low Volt.	V_{OL}	-	0	_	0.3	V
Supply Current	I_{DD}	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	8.2	16.5	33.0	mA

^{*} Note: Please design the VOP adjustment circuit on customer's main board



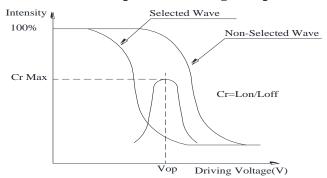


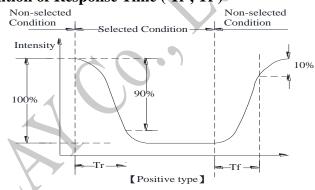
6.Optical Characteristics

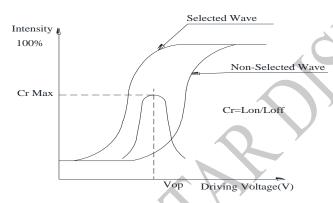
Item	Symbol	Condition	Min	Тур	Max	Unit
	heta	CR≧2	0	_	20	$\phi = 180^{\circ}$
7.7' A 1	θ	CR≧2	0	_	40	$\phi = 0^{\circ}$
View Angle	θ	CR≧2	0	_	30	$\phi = 90^{\circ}$
	θ	CR≧2	0	_	30	$\phi = 270^{\circ}$
Contrast Ratio	CR	_	—	3	_	_
D	T rise	_	—	200	300	ms
Response Time	T fall	_	_	250	350	ms

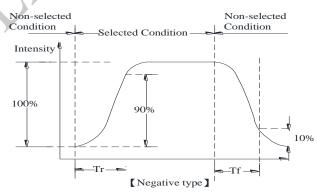
Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)Non-selected







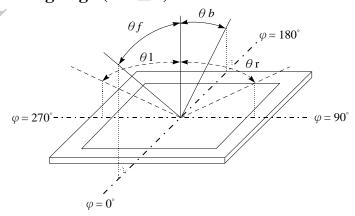


Conditions:

Operating Voltage: Vop Frame Frequency: 64 HZ Viewing Angle(θ , φ): 0° , 0°

Driving Waveform: 1/N duty, 1/a bias

Definition of viewing angle $(CR \ge 2)$



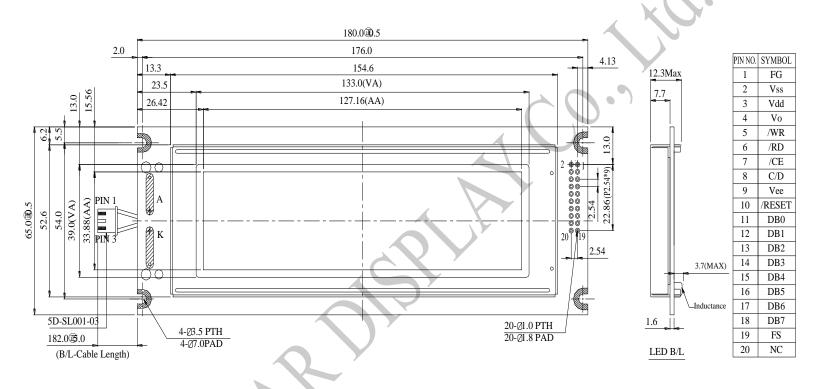


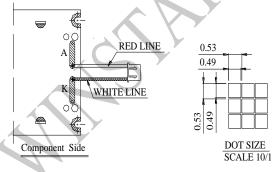
7.Interface Pin Function

Pin No.	Symbol	Level	Description
1	FG	-	Frame ground (Connected to bezel)
2	Vss	-	GND
3	Vdd	-	Power supply
4	Vo	-	Power supply for LCD driver
5	/WR	L	Data write. Write data into RA6963 when WR = L
6	/RD	L	Data read. Read data from RA6963 when RD = L
7	/CE	L	L : Chip enable
8	C/D	H/L	WR=L, C/D=H: Command Write C/D=L: Data write
			RD=L, C/D=H: Status Read C/D=L: Data read
9	Vee	-	Negative voltage output
10	/RESET	H/L	H: Normal; L: Initialize RA6963
11	DB0	H/L	Data bus line
12	DB1	H/L	Data bus line
13	DB2	H/L	Data bus line
14	DB3	H/L	Data bus line
15	DB4	H/L	Data bus line
16	DB5	H/L	Data bus line
17	DB6	H/L	Data bus line
18	DB7	H/L	Data bus line
19	FS	H/L	Pins for selection of font; H: 6 * 8, L: 8 * 8
20	NC		No connection



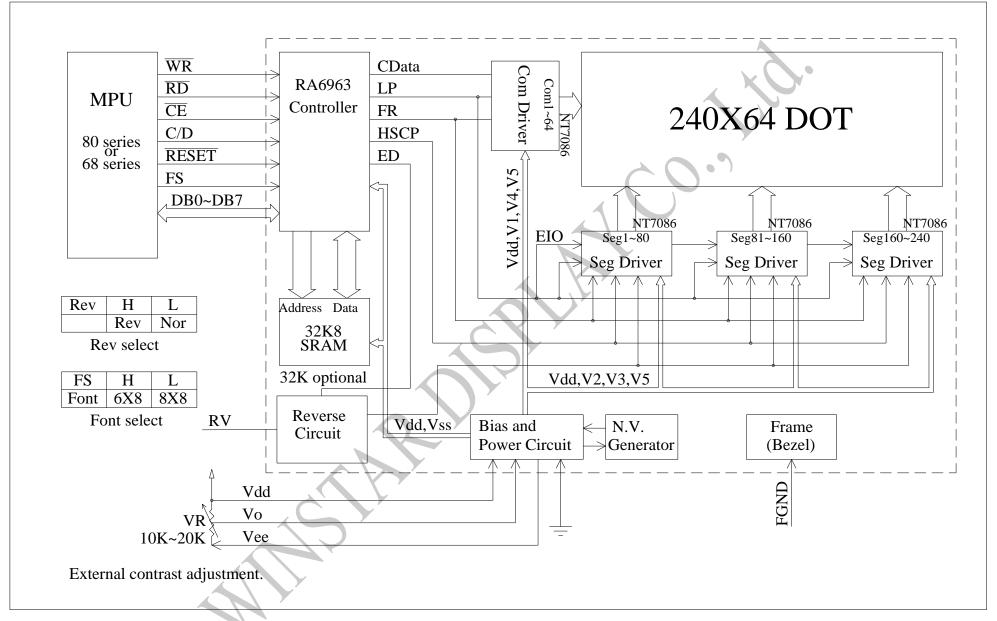
8.Contour Drawing & Block Diagram





The non-specified tolerance of dimension is **3.**3 mm.







9.Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

Environmental Test					
Test Item	Content of Test	Test Condition	Not e		
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2		
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2		
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs			
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1		
High Temperature/ Humidity storage	The module should be allowed to stand at 60 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2		
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles			
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3		
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times			

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.



10.Backlight Information

Specification

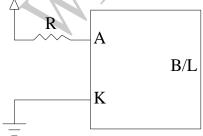
PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	25	80	100	mA	V=3.5V(Note 1)
Supply Voltage	V	3.4	3.5	3.6	V	- k 0
Reverse Voltage	VR	_	_	5	V	-
Luminance (Without LCD)	IV	520	650	_	cd/m ²	ILED=80mA
LED Life Time (For Reference only)	_	_	50K	-	Hr.	ILED=80mA 25℃,50-60%RH, (Note 2)
Color	White			Y		

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1: Supply current minimum value is only for reference since LED brightness efficacy keeps enhancing. Current consumption becomes less and less to achieve the same luminance.

Note 2:50K hours is only an estimate for reference.

LED B\L Drive Method 1.Drive from A , K





11.Inspection specification

NO	Item	Criterion				AQL
		Missing vertical	, horizonta	al segment, segment	nt contrast defect.	
		Missing characte	er, dot or	icon.		
		Display malfund	ction.			
01	Electrical	No function or r	no display.			0.65
UI	Testing	Current consum	ption exce	eds product specif	ications.	0.03
		LCD viewing ar	ngle defect	•	V ()	
		Mixed product t	ypes.		4	,
		Contrast defect.				
	Black or	2.1 White and b	lack spots	on display ≤ 0.25	mm, no more than	
02	white spots on	three white or bl	-			2.5
02	LCD (display		-	-	or lines within 3mm	2.5
	only)	-				
		3.1 Round type	: As follov	ving drawing		
		$\Phi = (x + y) / 2$		SIZE	Acceptable Q TY	
			4	Φ≦0.10	Accept no dense	
				$0.10 < \Phi \le 0.20$	2	
		4		$0.20 < \Phi \leq 0.25$	1	2.5
				0.25<Φ	0	
	LCD black	X				
	spots, white	→	<u> </u>			
03	spots,	. • .	\mathbf{x}^{Y}			
	contamination		T			
	(non-display)	3.2 Line type : (As follow	ng drawing)		
	1		Length	Width	Acceptable Q TY	
		~ /¥ <u>w</u>		W≦0.02	Accept no dense	
1		→ L +	L≦3.0	$0.02 < W \le 0.03$	_ 2	2.5
			L≦2.5	$0.03 < W \le 0.05$	2	
1				0.05 < W	As round type	



Polarizer bubbles Polarizer bubbles If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.	Size Φ $Φ \le 0.20$ $0.20 < Φ \le 0.50$ $0.50 < Φ \le 1.00$ $1.00 < Φ$ $Total Q TY$	Acceptable Q TY Accept no dense 3 2 0 3	2.5
---	---	---	-----



NO	Item	Criterion			AQL
05	Scratches	Follow NO.3 LCD blace	ck spots, white spots, co	ntamination	
		Symbols Define:			
		x: Chip length y	: Chip width z: Ch	nip thickness	
		k: Seal width t	: Glass thickness a: LC	CD side length	
		L: Electrode pad length	1:		
		6.1 General glass chip			
		6.1.1 Chip on panel sur	rface and crack between	panels:	
				NA PARTY NAMED IN COLUMN TO THE PARTY NAMED I	
		z: Chip thickness	y: Chip width	x: Chip length	
06	Chipped	Z≦1/2t	Not over viewing area	x ≤ 1/8a	2.5
	glass	$1/2t < z \le 2t$	Not exceed 1/3k	x ≤ 1/8a	
		⊙ If there are 2 or mor 6.1.2 Corner crack:	e chips, x is total length	of each chip.	
	A	z: Chip thickness	y: Chip width	x: Chip length	
		$Z \le 1/2t$	Not over viewing	$x \le 1/8a$	
1	N Y		area	Λ=1/00	
		$1/2t < z \le 2t$	Not exceed 1/3k	x ≤ 1/8a	
		⊙ If there are 2 or mor	e chips, x is the total len	gth of each chip.	



NO	Item	Criterion			AQL
		Symbols:			
		x: Chip length y: Chip wid	th z: Chip t	hickness	
		k: Seal width t: Glass thic		side length	
		L: Electrode pad length		_	
		6.2 Protrusion over terminal :			
		6.2.1 Chip on electrode pad :			
06	Glass	y: Chip width x : Chip $y \le 0.5$ mm $x \le 1/8$ a 6.2.2 Non-conductive portion:	length z:	$\begin{array}{c c} \text{Chip thickness} \\ < z \leqq t \end{array}$	2.5
		y: Chip width x: C	hip length	z: Chip thickness	
		$y \le L$ $x \le 1$		$0 < z \leq t$	
	_	remain and be inspected according. If the product will be heat sealer	_	_	
		be damaged.	a of the custome	or, are ungillion mark not	
4		6.2.3 Substrate protuberance and	internal crack.		
		× -		v. longth	
			y: width $y \le 1/3L$	$x: length$ $x \le a$	
		V L	y <u>= 1/3</u> L	Λ = α	
		N			



NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
		8.1 Illumination source flickers when lit.	0.65
08	Backlight	8.2 Spots or scratched that appear when lit must be judged.	2.5
	elements	Using LCD spot, lines and contamination standards.	
		8.3 Backlight doesn't light or color wrong.	0.65
		9.1 Bezel may not have rust, be deformed or have fingerprints,	2.5
09	Bezel	stains or other contamination.	
		9.2 Bezel must comply with job specifications.	0.65
		10.1 COB seal may not have pinholes larger than 0.2mm or contamination.	2.5
		10.2 COB seal surface may not have pinholes through to the IC.	2.5
		10.3 The height of the COB should not exceed the height	0.65
		indicated in the assembly diagram.	
		10.4 There may not be more than 2mm of sealant outside the	2.5
		seal area on the PCB. And there should be no more than three	
		places.	
		10.5 No oxidation or contamination PCB terminals.	2.5
10	PCB · COB	10.6 Parts on PCB must be the same as on the production	0.65
10	TCB COB	characteristic chart. There should be no wrong parts, missing	
		parts or excess parts.	
		10.7 The jumper on the PCB should conform to the product	0.65
		characteristic chart.	
		10.8 If solder gets on bezel tab pads, LED pad, zebra pad or	2.5
		screw hold pad, make sure it is smoothed down.	
		10.9 The Scraping testing standard for Copper Coating of PCB	2.5
		x	
	15	$X * Y \leq 2mm^2$	
		11.1 No un-melted solder paste may be present on the PCB.	2.5
	\ \\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	11.2 No cold solder joints, missing solder connections,	2.5
11	Soldering	oxidation or icicle.	
		11.3 No residue or solder balls on PCB.	2.5
		11.4 No short circuits in components on PCB.	0.65



NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface	2.5
		Pin (OLB) of TCP.	
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface	2.5
		pin must be present or look as if it cause the interface pin to sever.	
	General	12.6 The residual rosin or tin oil of soldering (component or chip	2.5
12		component) is not burned into brown or black color.	
	appearance	12.7 Sealant on top of the ITO circuit has not hardened.	2.5
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging	0.65
		specification sheet.	
		12.11 Product dimension and structure must conform to product	0.65
		specification sheet.	
		12.12 Visual defect outside of VA is not considered to be rejection.	0.65



12.Material List of Components for

RoHs

1. WINSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

- 2.Process for RoHS requirement : (only for RoHS inspection)
 - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.



13. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.





1 Panel Specification	• 1 N7 1		Feedback Sheet
1. Panel Type :			Page: 1
2. View Direction:		□ Pacc	□NG
3. Numbers of Dots: Pass NG 4. View Area: Pass NG 5. Active Area: Pass NG 6. Operating Temperature: Pass NG 7. Storage Temperature: Pass NG 8. Others: Pass NG 2. Mechanical Specification: Pass NG 1. PCB Size: Pass NG 2. Frame Size: Pass NG 3. Materal of Frame: Pass NG 4. Connector Position: Pass NG 5. Fix Hole Position: Pass NG 6. Backlight Position: Pass NG 7. Thickness of PCB: Pass NG 8. Height of Frame to PCB: Pass NG 9. Height of Module: Pass NG 10. Others: Pass NG 3. Relative Hole Size: Pass NG 1. Pitch of Connector: Pass NG 2. Hole size of Connector: Pass NG 3. Mounting Hole Type: Pass NG 4. Mounting Hole Type: Pass NG	• •		
4. View Area : Pass NG . 5. Active Area : Pass NG . 6. Operating Temperature : Pass NG . 7. Storage Temperature : Pass NG . 8. Others : Pass NG . 2. Mechanical Specification : Pass NG . 1. PCB Size : Pass NG . 2. Frame Size : Pass NG . 3. Materal of Frame : Pass NG . 4. Connector Position : Pass NG . 5. Fix Hole Position : Pass NG . 6. Backlight Position : Pass NG . 7. Thickness of PCB : Pass NG . 8. Height of Frame to PCB : Pass NG . 9. Height of Module : Pass NG . 10. Others : Pass NG . 3 * Relative Hole Size : Pass NG . 1. Pitch of Connector : Pass NG . 2. Hole size of Connector : Pass NG . 3. Mounting Hole Type : Pass NG . 4. Mounting Hole Type : Pass NG . 5.			<u> </u>
5. Active Area : Pass NG , 6. Operating Temperature : Pass NG , 7. Storage Temperature : Pass NG , 8. Others : Pass NG , 2. Mechanical Specification : Pass NG , 1. PCB Size : Pass NG , 2. Frame Size : Pass NG , 3. Materal of Frame : Pass NG , 4. Connector Position : Pass NG , 5. Fix Hole Position : Pass NG , 6. Backlight Position : Pass NG , 7. Thickness of PCB : Pass NG , 8. Height of Frame to PCB : Pass NG , 9. Height of Module : Pass NG , 10. Others : Pass NG , 1 Pitch of Connector : Pass NG , 2 Hole size of Connector : Pass NG , 3 Mounting Hole size : Pass NG , 4 Nacklight Specification : Pass NG , 5. Others : Pass NG ,			
A			
7. Storage Temperature : Pass NG . 8. Others :		_	
8. Others: 2 \ Mechanical Specification 1. PCB Size: Pass NG 2. Frame Size: Pass NG 3. Materal of Frame: Pass NG 4. Connector Position: Pass NG 5. Fix Hole Position: Pass NG 6. Backlight Position: Pass NG 7. Thickness of PCB: Pass NG 8. Height of Frame to PCB: Pass NG 9. Height of Module: Pass NG 10. Others: Pass NG 3 Relative Hole Size: Pass NG 1. Pitch of Connector: Pass NG 2. Hole size of Connector: Pass NG 3. Mounting Hole size: Pass NG 4. Mounting Hole Type: Pass NG 5. Others: Pass NG 4. Backlight Specification: 1 Bh/L Type: Pass NG 2. B/L Color: Pass NG Pass NG 3. B/L Driving Voltage (Reference for LED Type): Pass NG 5. Brightness of B/L: Pass NG		_	
2 \ Mechanical Specification 1. PCB Size :			l NG,
1. PCB Size :	_		
2. Frame Size : Pass NG 3. Materal of Frame : Pass NG 4. Connector Position : Pass NG 5. Fix Hole Position : Pass NG 6. Backlight Position : Pass NG 7. Thickness of PCB : Pass NG 8. Height of Frame to PCB : Pass NG 9. Height of Module : Pass NG 10. Others : Pass NG 3. Relative Hole Size : Pass NG 1. Pitch of Connector : Pass NG 2. Hole size of Connector : Pass NG 3. Mounting Hole size : Pass NG 4. Mounting Hole Type : Pass NG 5. Others : Pass NG 4. Backlight Specification : Pass NG 1. B/L Type : Pass NG 2. B/L Color : Pass NG 3. B/L Driving Voltage (Reference for LED Type) : Pass NG 5. Brightness of B/L : Pass NG 6. B/L Solder Method : Pass NG 7. Others :		□ Pass	
3. Materal of Frame :			
4. Connector Position : Pass NG , 5. Fix Hole Position : Pass NG , 6. Backlight Position : Pass NG , 7. Thickness of PCB : Pass NG , 8. Height of Frame to PCB : Pass NG , 9. Height of Module : Pass NG , 10. Others : Pass NG , 3. Relative Hole Size : Pass NG , 1. Pitch of Connector : Pass NG , 2. Hole size of Connector : Pass NG , 3. Mounting Hole size : Pass NG , 4. Mounting Hole Type : Pass NG , 5. Others : Pass NG , 4. Backlight Specification : Pass NG , 1. B/L Type : Pass NG , 2. B/L Color : Pass NG , 3. B/L Driving Voltage (Reference for LED Type) : Pass NG , 4. B/L Driving Current : Pass NG , 5. Brightness of B/L : Pass NG , 6. B/L Solder Method : Pass NG ,			
5. Fix Hole Position : Pass NG , 6. Backlight Position : Pass NG , 7. Thickness of PCB : Pass NG , 8. Height of Frame to PCB : Pass NG , 9. Height of Module : Pass NG , 10. Others : Pass NG , 3. Relative Hole Size : Pass NG , 1. Pitch of Connector : Pass NG , 2. Hole size of Connector : Pass NG , 3. Mounting Hole size : Pass NG , 4. Mounting Hole Type : Pass NG , 5. Others : Pass NG , 4. Backlight Specification : Pass NG , 1. B/L Type : Pass NG , 2. B/L Color : Pass NG , 3. B/L Driving Voltage (Reference for LED Type) : Pass NG , 4. B/L Driving Current : Pass NG , 5. Brightness of B/L : Pass NG , 6. B/L Solder Method : Pass NG ,			
6. Backlight Position : Pass NG , 7. Thickness of PCB : Pass NG , 8. Height of Frame to PCB : Pass NG , 9. Height of Module : Pass NG , 10. Others :			
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8. Height of Frame to PCB : Pass NG , 9. Height of Module : Pass NG , 10. Others : Pass NG , 3 * Relative Hole Size : Pass NG , 1. Pitch of Connector : Pass NG , 2. Hole size of Connector : Pass NG , 3. Mounting Hole size : Pass NG , 4. Mounting Hole Type : Pass NG , 5. Others : Pass NG , 4 * Backlight Specification : 1. B/L Type : Pass NG , 2. B/L Color : Pass NG , 3. B/L Driving Voltage (Reference for LED Type) : Pass NG , 4. B/L Driving Current : Pass NG , 5. Brightness of B/L : Pass NG , 6. B/L Solder Method : Pass NG , 7. Others : Pass NG ,	<u> </u>		
9. Height of Module : Pass NG , 10. Others : Pass NG , 3 · Relative Hole Size : Pass NG , 1. Pitch of Connector : Pass NG , 2. Hole size of Connector : Pass NG , 3. Mounting Hole size : Pass NG , 4. Mounting Hole Type : Pass NG , 5. Others : Pass NG , 4 · Backlight Specification : Pass NG , 1. B/L Type : Pass NG , 2. B/L Color : Pass NG , 3. B/L Driving Voltage (Reference for LED Type) : Pass NG , 4. B/L Driving Current : Pass NG , 5. Brightness of B/L : Pass NG , 6. B/L Solder Method : Pass NG , 7. Others : Pass NG ,			
10. Others :	C		
3	C		
1. Pitch of Connector : Pass NG , 2. Hole size of Connector : Pass NG , 3. Mounting Hole size : Pass NG , 4. Mounting Hole Type : Pass NG , 5. Others : Pass NG , 4. Backlight Specification : Pass NG , 1. B/L Type : Pass NG , 2. B/L Color : Pass NG , 3. B/L Driving Voltage (Reference for LED Type) : Pass NG , 4. B/L Driving Current : Pass NG , 5. Brightness of B/L : Pass NG , 6. B/L Solder Method : Pass NG , 7. Others : Pass NG ,			
2. Hole size of Connector : Pass NG , 3. Mounting Hole size : Pass NG , 4. Mounting Hole Type : Pass NG , 5. Others : Pass NG , 4. Backlight Specification : Pass NG , 1. B/L Type : Pass NG , 2. B/L Color : Pass NG , 3. B/L Driving Voltage (Reference for LED Type) : Pass NG , 4. B/L Driving Current : Pass NG , 5. Brightness of B/L : Pass NG , 6. B/L Solder Method : Pass NG , 7. Others : Pass NG ,		Pass	\sqcap NG
3. Mounting Hole size : Pass NG , 4. Mounting Hole Type : Pass NG , 5. Others : Pass NG , 4. Backlight Specification : Pass NG , 1. B/L Type : Pass NG , 2. B/L Color : Pass NG , 3. B/L Driving Voltage (Reference for LED Type) : Pass NG , 4. B/L Driving Current : Pass NG , 5. Brightness of B/L : Pass NG , 6. B/L Solder Method : Pass NG , 7. Others : Pass NG ,			
4. Mounting Hole Type : Pass NG , 5. Others : Pass NG , 4. Backlight Specification : NG , 1. B/L Type : Pass NG , 2. B/L Color : Pass NG , 3. B/L Driving Voltage (Reference for LED Type) : Pass NG , 4. B/L Driving Current : Pass NG , 5. Brightness of B/L : Pass NG , 6. B/L Solder Method : Pass NG , 7. Others : Pass NG ,			
5. Others: Pass NG, 4 · Backlight Specification:			
4 · Backlight Specification : 1. B/L Type : Pass 2. B/L Color : Pass 3. B/L Driving Voltage (Reference for LED Type) : Pass 4. B/L Driving Current : Pass 5. Brightness of B/L : Pass 6. B/L Solder Method : Pass 7. Others : Pass NG ,			
1. B/L Type : Pass NG , 2. B/L Color : Pass NG , 3. B/L Driving Voltage (Reference for LED Type) : Pass NG , 4. B/L Driving Current : Pass NG , 5. Brightness of B/L : Pass NG , 6. B/L Solder Method : Pass NG , 7. Others : Pass NG ,			
2. B/L Color:		☐ Pass	\sqcap NG.
3. B/L Driving Voltage (Reference for LED Type):			
4. B/L Driving Current:			
5. Brightness of B/L : □ Pass □ NG , 6. B/L Solder Method : □ Pass □ NG , 7. Others : □ Pass □ NG ,			
6. B/L Solder Method : ☐ Pass ☐ NG ,	G		
7. Others:	-		
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5 \ <u>Elec</u>	umber :		Page: 2
	ctronic Characteristics of	Module:	
1. Inp	out Voltage:	☐ Pass	□ NG ,
2. Su	pply Current:	☐ Pass	\square NG ,
3. Dr	iving Voltage for LCD:	Pass	□ NG ,
4. Co	ntrast for LCD:	☐ Pass	□ NG ,
5. B/I	L Driving Method:	☐ Pass	□ NG ,
6. Ne	gative Voltage Output:	☐ Pass	□ NG ,
7. Int	erface Function:	Pass	□ NG ,
8. LC	D Uniformity:	Pass	□ NG ,
9. ES	D test:	Pass	□ NG,
10. Otl	hers:	☐ Pass	□ NG,
6 - <u>Su</u>	mmary:		